

VIA Mobile360 M810

Fanless ultra-compact in-vehicle solution for flexible 360° SVS, ADAS and DMS configurations

Features

- Six FAKRA connectors
- Two CAN bus ports
- AWS IoT Greengrass qualified
- VIA ADAS technology including FCW, BSD, LDW and DMOD
- VIA SVS technology enabling real-time 360° panoramic display

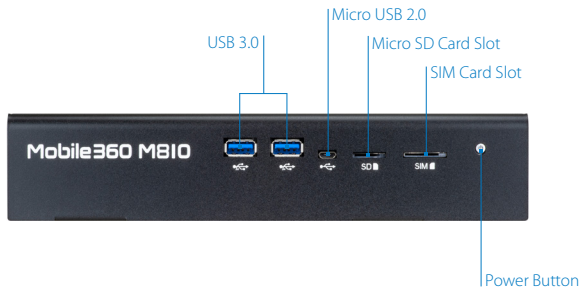


Specifications

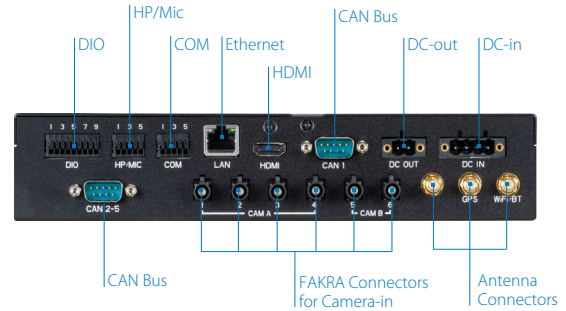
Model Name	Mobile360 M810
Processor	Qualcomm® APQ8096A Embedded Processor - Two high-performance Kryo cores up to 2.054GHz - Two low power Kryo cores up to 1.593GHz
System Memory	4GB LPDDR4 SDRAM
Storage	16GB eMMC flash memory 2 M.2 SATA slots
Graphics	Qualcomm® Adreno™ 530 GPU 3D graphics accelerator with 64-bit addressing 624MHz Graphics engine supporting OpenGL ES 3.1/GEP, GL4.4, DX11.3/4, OpenCL 2.0, Renderscript-Next Supports H.264, VP8, HEVC 8/10-bit, VP9 video decoding up to: 4K@60fps, 1080p@240fps, 8 x 1080p@30fps
Camera-in Interface	2 DS90UB964-Q1 Quad FPD-Link III deserializer Hub
LAN	RTL8111G Ethernet Controller
Wireless Connectivity	AMPAK AP12356_I1 MiniPCIe Wi-Fi/BT 4.1 module MAX-M8Q-0-10 u-blox 8 GNSS module
Audio	TI 6PAIC3104IRHBRQ1 Audio Codec
HDMI	Integrated HDMI 2.0 transmitter
Expansion I/O	1 MiniPCIe slot (USB only) for 4G module 1 MiniPCIe slot (PCIe/USB) for Wi-Fi/BT module
Front Panel I/O	2 USB 3.0 ports 1 Micro USB 2.0 port (for debugging) 1 Micro SD card slot 1 SIM card slot (optional) 1 Power button
Back Panel I/O	1 HDMI port 1 DIO port 1 COM port 2 CAN bus ports (supports up to five CAN bus) 1 Gigabit Ethernet port 6 FAKRA connectors for camera-in 1 Headphone/Mic-in connector 3 Antenna connectors for Wi-Fi/BT, GPS, and 4G (factory option) 1 4-pole Phoenix 9~36V DC-in 1 2-pole Phoenix 12V DC-out
Power Supply	9~36V DC-in with IGN
Operating System	Yocto 2.3
Operating Temperature	-20°C ~ 70°C
Storage Temperature	-20°C ~ 70°C
Operating Humidity	0~95% (non-condensing)
Vibration Loading During Operation	ISO-16750-3 compliance
Shock During Operation	ISO-16750-3 compliance



Front Panel External I/O



Back Panel External I/O



Specifications

Model Name	Mobile360 M810
Mechanical Construction	Metal chassis housing
Dimensions	236.7mm(W) x 46mm(H) x 180mm(D) (9.32" x 1.81" x 7.09")
Weight	2.2kg (4.85lbs)
Compliance	CE, FCC, UKCA, E-Mark

Ordering Information

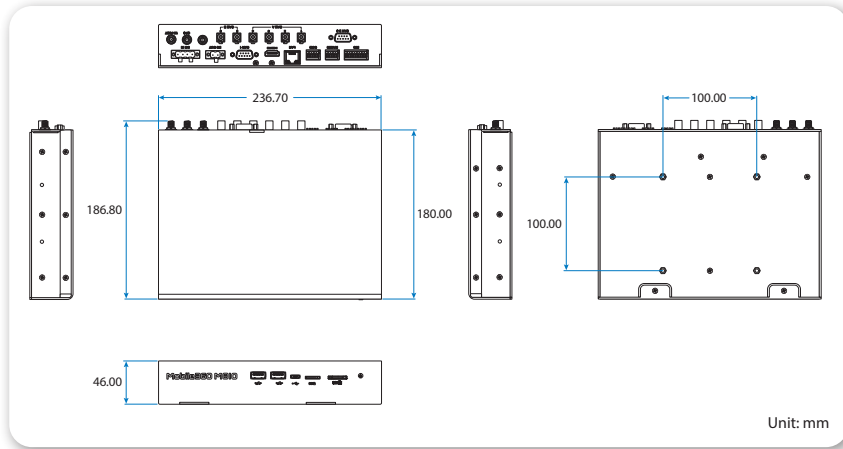
Part Number	SoC Frequency	Description
M360-810-1Q20A2	Qualcomm® APQ8096A Embedded Processor @ 2.054GHz/1.593GHz	Fanless mobile system with 2.054GHz Qualcomm® APQ8096A Embedded Processor, 4GB LPDDR4 SDRAM, HDMI, 2 USB 3.0, Micro USB 2.0 (debugging), DIO, COM, 2 CAN bus, Gigabit Ethernet, 6 FAKRA connectors for camera-in, Wi-Fi, Bluetooth 4.1, GPS, Micro SD card slot, 2 M.2 slots, 12V DC-out, 9~36V DC-in with IGN

Optional Accessories

Camera Accessories	
Part Number	Description
M360-ADAS-1C19A1	1.0MP FOV-35 720p CMOS Front ADAS camera with microphone, speaker and mounting bracket
M360-DMS-1C19A1	1.0MP FOV-62 720p CMOS DMS camera with IR and mounting bracket
99G40-08115Z	1.0MP FOV-35 720p CMOS automotive-grade camera for BSD
99G40-08116Z	1.0MP FOV-192 720p CMOS automotive-grade camera for SVS + Rear ADAS
99G33-230406	15M FAKRA cable
M360-CBKT-00A1	Camera mounting bracket for SVS/BSD 42mm x 28.2mm x 32.3mm (1.65" x 1.11" x 1.27")

Display Accessories	
Part Number	Description
99G73-01034C	10" Resistive touch monitor (1280x800)
99G73-01030C	7" Resistive touch monitor (1280x800)

Dimensions



Packing List

Items

- Mobile360 M810 system
- 2 Phoenix plug to DC jacks (DC-in & DC-out)
- COM cable (for debugging)
- GPS antenna
- 2 Wi-Fi/BT antennas
- CAN Extension cable